

Material Declaration Report

Package Type:	TQFN 56L
Pericom Package Code:	ZB56 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	144.0000
Termination Plating:	NiPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5~2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	2
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	2012/2/9

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	95.75330	GTK	Epoxy Resin A	Trade secret	5.00	4.78767
			Epoxy Resin B	Trade secret	2.50	2.39383
			Phenol Resin	Trade secret	5.00	4.78767
			Metal Hydroxide	Trade secret	3.00	2.87260
			Carbon black	1333-86-4	0.50	0.47877
			Silica fused	60676-86-0	68.50	65.59101
			Silica fused	7631-86-9	15.00	14.36300
			Silica crystalline	14808-60-7	0.50	0.47877
			LEADFRAME	44.64000		Copper
Iron	7439-89-6	2.31				1.03118
Zinc	7440-66-6	0.12				0.05357
Phosphorus	7723-14-0	0.08				0.03571
Nickel(Ni)	7440-02-0	1.58				0.70531
palladium(Pd)	7440-05-3	0.15				0.06696
SILICON DIE	2.93300		Silicon (Si)	7440-21-3	99.19	2.90930
			Non-hazardous Metal	Proprietary	0.81	0.02370
DIE ATTACH EPOXY	0.28770		Silver	7440-22-4	71.00	0.20427
			Epoxy resin A	9003-36-5	5.00	0.01439
			Epoxy resin B	Trade secret	6.00	0.01726
			Epoxy resin C	Trade secret	6.00	0.01726
			Acrylate	Trade secret	6.00	0.01726
			Phenolic Hardener	Trade secret	5.00	0.01439
			Dicyandiamide	461-58-5	0.30	0.00086
			Organic peroxide	Trade secret	0.70	0.00201
WIRE BOND	0.38600		Copper	7440-50-8	97.30	0.37558
			Palladium	7440-5-3	2.70	0.01042

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													
O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.																		